
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wen-chou Vincent Wang et al.

Attorney Docket No.:
ALTRP096/A1201

Application No.: Please assign

Examiner: Unknown

Filed: Herewith

Group: Unknown

Title: STRUCTURE AND MATERIAL FOR
ASSEMBLING A LOW-K SI DIE TO ACHIEVE A
LOW WARPAGE AND INDUSTRIAL GRADE
RELIABILITY FLIP CHIP PACKAGE WITH
ORGANIC SUBSTRATE

CERTIFICATE OF EXPRESS MAILING I hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on November 20, 2003 in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number EV 332826161 US, addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Ryan Eachus

INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449 may be material to examination of the above-identified patent application. Applicants submit the list of these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application. Because the listed references were either cited by the PTO, or submitted to the PTO in the prior application, under 37 CFR § 1.98(d) Applicants submit that copies need not be provided.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office

Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. ALTRP096/A1202).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

A handwritten signature in black ink, appearing to read "Desmond Gean". The signature is fluid and cursive, with a large initial 'D'.

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Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	ALTRP096/A1201	To be assigned
	Applicant:	
	Wen-chou Vincent Wang et al.	
Filing Date	Group	
Herewith	Unknown	

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A						
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	U.S. Patent Application Serial No. 10/305,671 filed on November 25, 2002 entitled "Flip Chip Package With Warpage Control"
	P	
	Q	
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.